

KETEK GmbH Munich - Germany

SiPM Development at KETEK

- A short introduction to KETEK SiPM Products and Status with focus on small microcell SiPMs -





CALICE Collaboration Meeting

20-22 March 2013, Hamburg

Florian Wiest, KETEK GmbH

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KETEK SiPM Devices

- Technology
- GE of different microcell types
- Projects with small micro pixel sizes
- Ketek standard portfolio
- Status PM1125
- SiPM roadmap



KETEK SiPM Low Level Light Sensors

KETEK Silicon Photomultipliers

- Fast Single Photon Counting -
 - High PDE
 up to 60 % for 50µm cell type
 - Optimized for blue light sensitivity - 420 nm peak sensitivity
 - Low dark rate
 below 500 kHz/mm²
 - Low cross talk
 - below 25% at 20% OV, dep. on cell- and device type
 - Huge bias voltage range of stable operation - up to 30% overvoltage
 - Extremely low temperature coefficient - below 1% above 10% overvoltage



PM1150 - Prototype

1.0 x 1.0 mm ²
50 µm
no trench
70%
420 nm



Basic Construction of the KETEK Microcell



- Silicon P on N structure with high Geiger efficiency
- Shallow entrance window with high quantum efficiency
- Optimized geometrical fill factor
- ⇒ High photon detection efficiency
- Available in two technologies

KETEK Standard Technology

- Technology optimized for maximum GE
- Devices with very high PDE
- Particularly suitable for small microcells and small active area

KETEK Trench Technology

- Technology with improved optical barrier and low-RC readout
- Devices with low crosstalk and improved timing
- Particularly suitable for large microcells and large area devices



KETEK SiPM Microcell Types

Geometrical Efficiency





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Projects with small micro pixel sizes:

CERN CMS HCAL Upgrade



Chip Type A: - Active area: 4.84 mm²

- 12100 cells with 20 μm pitch
- PDE at 515nm: 20% ... 23%
- PDE at 420 nm: 30% ... 35%





Chip Type B:

Active area: 1.0 mm²
4384 cells with 15 μm pitch
PDE at 515nm: 14% ... 15%
PDE at 420 nm: 20% ... 23%



Chip Type C:

- Active area: 5.0 mm²

Wiest,

GmbH

- 22376 cells with 15 μm pitch
- PDE at 515nm: 17% ... 20%
- PDE at 420 nm: 22% ... 24%

KETEK Creative Detector Solutions

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20µm Cell Pitch Type Characteristic of Chip Type A (4.8 mm²):



Bias [V]

PDE Enhancement of 15µm Cell Pitch Type



CERN CMS Customized Chip (C):

Active Area:5.0 mm2Cell Pitch:15 μmGE (layout):47%

- Measurements performed by CERN / Iouri Musienko
- PDE is not affected by crosstalk and afterpulsing
- 22-24% PDE for blue light



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Scheduled Standard Portfolio in Plastic Package

• Four different package sizes

✓ ✓
PM11 – PM22 – PM33 – PM66

Five different micropixel sizes

25 μm – 50 μm – 60 μm – 75 μm – 100 μm

- Standard- and Trench Technology
- Pin- and SMD Version
- Most variants available until Mai 2013

3 x 3mm² active area; 50 µm cell type; peak wavelength 420 nm; plastic package







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First Results from PM1125

- Active area:
- Number of cells:
- Geometrical fill factor (according to design): 47%
- Dark current at 20% OV (and RT):





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PM1125 - SMD

 $1.2 \ x \ 1.2 \ mm^2$ active area; 25 μm cell type; peak wavelength 420 nm;



2304

< 0.5 µA

1.2 mm x 1.2 mm

First Results from PM1125

PM1125 Production Schedule

Testing of devices: CW 12 Dicing: CW 13

Packaging: CW 18

Testing and shipping:

CW 19 (until 10th of May)

1.95 "Bias" Supply GND 0.725 ±0.025 0.55 0.55 0.825 2.45 2.05 F. Active area 0.85 1.8 ±0.10



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PM1125 - SMD 1.2 x 1.2 mm² active area; 25 µm cell type; peak wavelength 420 nm;

Qualification Test Results – Environmental Stress Test

Test	Test Conditions	Qty	Target	Specification	Results
PC	Pre-conditioning / MSL classification	≥ 10	MSL3	Bake: 24h at 125°C Soak: 192h at 30°C/60%R.H. Reflow: 3 x Peak 255°C – 260°C	33/33 OK
HTS	High Temperature Storage (1000h @ 125°C)	≥ 10	0 failed parts	MSL3 Preconditioning 300h at 125° C + 170h at 125° C (470h) + 330h at 125° C (800h) + 200h at 125° C (1000h)	11/11 OK 11/11 OK 11/11 OK 11/11 OK 11/11 OK
H³TS	High Humidity High Temperature Storage (1000h @ 85°C/85 % rH)	≥ 10	0 failed parts	MSL3 Preconditioning 300h at 85° C/85rH + 170h at 125° (470h) + 330h at 125° (800h) + 200h at 125° (1000h)	11/11 OK 11/11 OK 11/11 OK 11/11 OK 11/11 OK
ESD*	ANSI/ESDA/JEDEC JS-001-2012– Human Body Model (HBM) – Component Level	≥ 10	0 failed parts	± 1kV ± 2kV	10/10 OK 10/10 OK

• Reflow soldering has to be performed under N2 atmosphere



KETEK SiPM Roadmap

- Completion of portfolio until Q2 / 2013
- Further noise reduction (DR, X-Talk)
 by enhancing the KETEK trench technology
- Devices with reduced capacitance and enhanced green light sensitivity
- Through silicon via technology
- Chip size package
- Arrays on package level



9-Channel SiPM-Array



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Silicon Drift Detectors with 7 mm² to 100 mm² active area for X-ray spectroscopy read more

VITUS SDD



VICO

Electronic components for optimised use of VITUS SDDs in OEM devices read more



AXAS Analytical X-ray Acquisition Systems complete with SDD, preamplifier and pulse processor read more

Accessories

equipment for

Detectors, e.g.

Silicon Drift

preamps, DPP

read more

etc.

Additional



OEM solution combines Silicon Drift Detector with preamplifier in optional housing read more

VIAMP

SiPM

Silicon Photo-

36 mm² active

area for low-level

light detection

1.4 mm² to

read more

multipliers with

NEWS

FOUNDATION OF...

Fraunhofer-Einrichtung für Modulare Festkörper-Technologien (EMFT), Siemens AG, LFoundry GmbH, KETEK... ...read more

NEW 50MM² HIGH-END...

KETEK is introducing its new 50mm² silicon drift detector with unpecedented guaranteed energy...

...read more

Thank you for your attention!

Additional Slides



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Discussion: KETEK Leadframe Solution for DESY / Uni Hamburg





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KETEK SIPM



Sensitive area - 2.2x2.2 mm² Package size (L×H×D) - 5.4x2.9x2.0 mm³ Pins go up Distance between the pins 2.54 mm



Picture of a tile with SiPM

Grooves for flexible pins

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Projects: CERN LHCB Fiber Tracker Upgrade



8250 µm

Geometry of device:

- 32 Bias Bondpads ("Bias") with GND Bond Frame
- Cell Pitch: 60 μm x 57.5 μm
- Quantity of cells: 88 per channel // 2816 per chip

First Spectroscopic results:

• PDE(410 nm) ~ 45% and XT ~ 5% for Trench-Version ("3A")!





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Radiation Hardness measured at CERN CMS

KETEK: LED amplitude vs. dVB

MPPC&KETEK: Dark Current vs. dV

